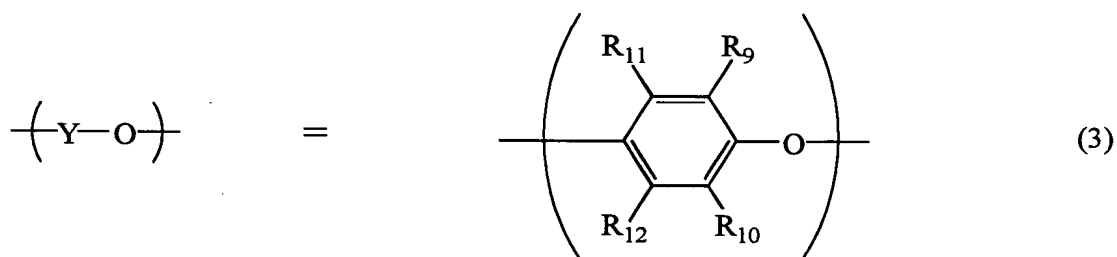
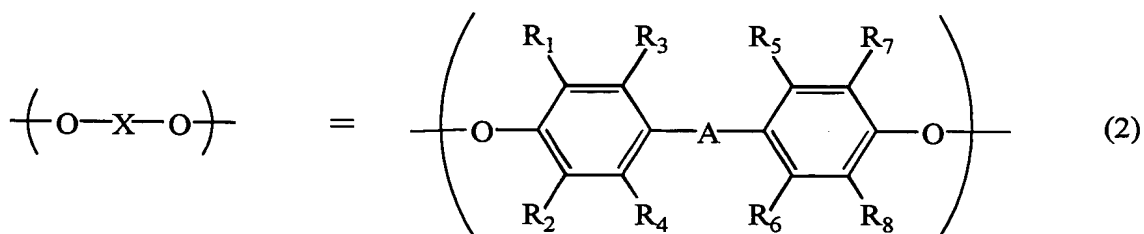
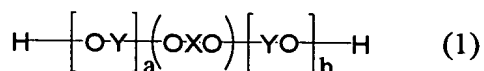


What is claimed is:

1. An epoxy resin curing agent having a number average molecular weight of 500 to 3,000, represented by the formula

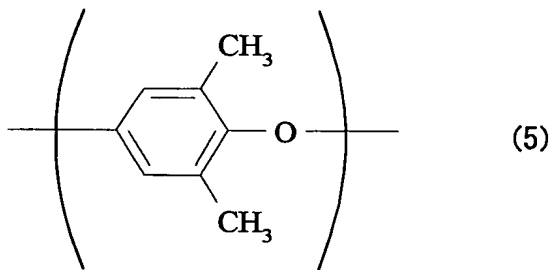
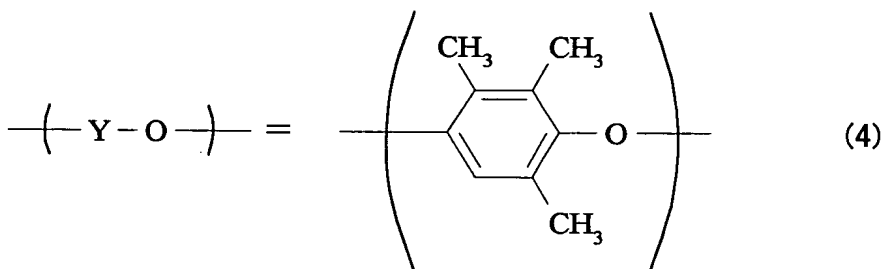
5 (1),



wherein $-(\text{O}-\text{X}-\text{O})-$ is represented by the formula (2)
 10 (in which R_1 , R_2 , R_7 and R_8 may be the same or different and are a halogen atom, an alkyl group having 6 or less carbon atoms or a phenyl group, R_3 , R_4 , R_5 and R_6 may be the same or different and are a hydrogen atom, a halogen atom, an alkyl group having
 6 or less carbon atoms or a phenyl group, and A is a direct
 15 bond or a linear, branched or cyclic hydrocarbon having 20 or less carbon atoms), $-(\text{Y}-\text{O})-$ is an arrangement of one kind of structure defined by the formula (3) or a random arrangement of at least two kinds of structures defined by the formula (3) (in which R_9 and R_{10} may be the same or different and are a halogen

atom, an alkyl group having 6 or less carbon atoms or a phenyl group and R_{11} and R_{12} may be the same or different and are a hydrogen atom, a halogen atom, an alkyl group having 6 or less carbon atoms or a phenyl group), and each of a and b is an integer of 0 to 30, provided that at least either a or b is not 0.

2. The epoxy resin curing agent according to claim 1, wherein R_1 , R_2 , R_7 and R_8 in $-(O-X-O)-$ of the formula (2) are a methyl group, and $-(Y-O)-$ has a structure of an arrangement of the formula (4) or the formula (5) or a random arrangement of the formula (4) and the formula (5),



3. The epoxy resin curing agent according to claim 2, wherein R_3 , R_4 , R_5 and R_6 in $-(O-X-O)-$ of the formula (2) are a hydrogen group.

4. The epoxy resin curing agent according to claim 2, wherein, in $-(O-X-O)-$ of the formula (2), R_3 and R_6 are a hydrogen group and R_4 and R_5 are a methyl group.

5. The epoxy resin curing agent according to claim 2,
wherein $-(Y-O)-$ is represented by the formula (5).

5 6. A curable epoxy resin composition containing an epoxy
resin and the epoxy resin curing agent recited in claim 1.

7. A cured product obtainable by curing the curable epoxy
resin composition recited in claim 6.

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